

REMARKS/ARGUMENTS

Overview of the invention: Unwanted thermal expansion of the main pole of a magnetic write head is prevented by thermally connecting the write coil to the substrate. This is done through a thermally conductive pedestal that extends upwards from the substrate and is in turn connected to the coil through a thermally conductive layer

Reconsideration is requested of all rejections based on objections to the abstract:

A new abstract that conforms to the guidelines provided by examiner has been provided.

Reconsideration is requested of the rejection of claims 1, 3, 4, 25, 27, and 28 under 35 U.S.C. 102(b) as being anticipated by Jensen et al.:

As currently amended, claim 1 reads as follows:

1. A method to conduct heat generated by a coil located within a structure, to a single substrate, when there is at least one thermally insulating layer between said coil and said substrate, comprising:

    forming a thermally conductive pedestal that originates at said substrate, and extends upwards therefrom;

    forming a layer of thermally conductive material that overlies said coil and extends beyond said coil to overlie said pedestal; and

    thermally connecting said coil to said substrate through said pedestal, thereby providing an unbroken thermal path between said coil and said substrate.

Examiner will have noticed that claim 1 is a description of our FIG. 5, so no new matter is involved.

We note the following differences between the method of claim 1 and Jensen et al.:

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(1) The present invention is directed to a structure having only a single substrate. As interpreted by examiner, Jensen provides a plurality of substrates (elements 512/518, 508/514, 510, and 506)

(2) There is NO thermally insulating layer between Jensen's coil and his substrate 518/512 since, as examiner points out, Jensen states that layer 532 has high thermal conductivity i.e. it is not thermally insulating.

(3) Jensen does not teach a thermally conductive layer that overlies his coil (shown as layer 41 in FIG. 5 of the present invention).

(4) Jensen's "pedestals", interpreted by examiner to be elements 522 or 524, do not make thermal contact with a thermally conductive layer that overlies his coil.

Reconsideration is requested of the rejection of claims 2, 5, 6, 26, and 29 under 35 U.S.C. 103(a) as being unpatentable over Jensen et al.

Applicant believes that claims 1 and 25, as currently amended, clearly distinguish the present invention from Jensen et al. See detailed discussion above. Since claims 2, 5, 6, 26, and 29 are all dependent on one or other of these, their rejection under 35 USC 103(a) is now rendered moot.

Applicant respectfully requests that a timely Notice of Allowance be issued in this case.

Respectfully submitted,

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By



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